

Application No. 10/710,260
Technology Center 2884
Amendment dated September 22, 2006
Reply to Office Action dated May 22, 2006

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently amended): An optical sensor package comprising:
a substrate having a first surface in which a cavity is defined, a second surface opposite the first surface, and a wall between the cavity and the second surface, at least a portion of the substrate being formed of silicon;
a membrane bonded to the substrate and spanning the cavity in the substrate;
an optical sensing element on the membrane; and
a window located at the second surface so that infrared radiation passes for enabling infrared radiation to pass through the wall of the substrate, through the cavity, and then to the optical sensing element.
element, the wall allowing only radiation of wavelengths longer than 1.1 micrometers to pass therethrough to the optical sensing element.

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Claim 2 (Original): The optical sensor package according to claim 1,
wherein the optical sensing element is a thermopile.

Claim 3 (Original): The optical sensor package according to claim 1,
further comprising integrated circuitry on the substrate, the integrated circuitry
performing logic functions and signal processing for the optical sensing
element.

Claim 4 (Original): The optical sensor package according to claim 3,
wherein the integrated circuitry is between the membrane and the substrate.

Claim 5 (Currently amended): The optical sensor package according
to claim 1, wherein the substrate and the wall are defined by a
monocrystallographic silicon chip and the wall only allows radiation of
wavelengths longer than 1.1 micrometers to pass therethrough to the optical
sensing element.

Claim 6 (Original): The optical sensor package according to claim 1,
further comprising a filtering material at the second surface of the substrate.

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Claim 7 (Original): The optical sensor package according to claim 6,
wherein the filtering material is implanted in the second surface of the
substrate.

Claim 8 (Original): The optical sensor package according to claim 6,
wherein the filtering material is epitaxially grown on the second surface of the
substrate.

Claim 9 (Original): The optical sensor package according to claim 6,
wherein the filtering material is a first chip that constitutes a first portion of the
substrate, the cavity is defined in a silicon chip that constitutes a second portion
of the substrate, and the first and silicon chips are bonded together to form the
substrate.

Claim 10 (Original): The optical sensor package according to claim
6, wherein the filtering material is chosen from the group consisting of
germanium, PbS, InAs, and PbTe.

Claim 11 (Original): The optical sensor package according to claim
1, further comprising an antireflection coating on the second surface of the

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substrate, the antireflection coating minimizing reflection of infrared radiation by the substrate.

Claim 12 (Original): The optical sensor package according to claim 11, wherein the window comprises a coating on the antireflection coating, the coating being substantially opaque to infrared radiation and having an opening aligned with the wall of the substrate and the optical sensing element on the membrane.

Claim 13 (Original): The optical sensor package according to claim 1, further comprising a capping chip secured to the substrate and enclosing the membrane.

Claim 14 (Currently amended): An infrared sensor package comprising:

a substrate having a first surface in which a cavity is defined, a second surface opposite the first surface, and a wall defined by and between the cavity and the second surface, at least a portion of the substrate being formed of silicon;

a membrane bonded to the substrate and spanning the cavity in the

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substrate;

a thermopile sensing element on the membrane; and
integrated circuitry on the substrate, the integrated circuitry
performing logic functions and signal processing for the thermopile sensing
element;

a window located at the second surface so that infrared radiation
passes for enabling infrared radiation to pass through the wall of the
substrate, through the cavity, and then to the thermopile sensing element.

Claim 15 (Original): The infrared sensor package according to claim
14, wherein the wall is defined by the silicon portion of the substrate.

Claim 16 (Original): The infrared sensor package according to claim
14, wherein the substrate and the wall are defined by a monocrystallographic
silicon chip.

Claim 17 (Original): The infrared sensor package according to claim
14, further comprising a filtering material implanted in the second surface of the
substrate.

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Claim 18 (Original): The infrared sensor package according to claim 14, further comprising a filtering material epitaxially grown on the second surface of the substrate.

Claim 19 (Original): The infrared sensor package according to claim 14, wherein the substrate comprises a first chip of a filtering material bonded to a silicon chip in which the cavity is defined.

Claim 20 (Original): The infrared sensor package according to claim 14, further comprising a capping chip secured to the substrate and defining a cavity that encloses the membrane.